

Title (en)

Gold wire for semiconductor element connection and semiconductor element connection method

Title (de)

Golddraht für Halbleiterverbindungsbauelement und Verfahren zur Herstellung eines Halbleiterverbindungsbauelementes

Title (fr)

Fil d'or pour composant de connection à semi-conducteur et procédé de fabrication d'un composant de connection à semi-conducteur

Publication

EP 1160344 B1 20091216 (EN)

Application

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Priority

JP 2000166524 A 20000531

Abstract (en)

[origin: EP1160344A1] A gold wire, for semiconductor element connection, consisting of 5-100 ppm by weight of Ca, 5-100 ppm by weight of Gd, 1-100 ppm by weight of Y and preferably 1-100 ppm by weight of at least one from among rare earth elements other than Y, as well as 1-100 ppm by weight of at least one from among Mg, Ti and Pb, the total amount of these elements being no greater than 200 ppm by weight, the balance being gold and unavoidable impurities. A semiconductor element connection method by ball bonding or bump connection using the gold wire.

IPC 8 full level

C22C 5/02 (2006.01); **B23K 20/00** (2006.01); **H01L 21/60** (2006.01); **H01L 23/49** (2006.01)

CPC (source: EP KR US)

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